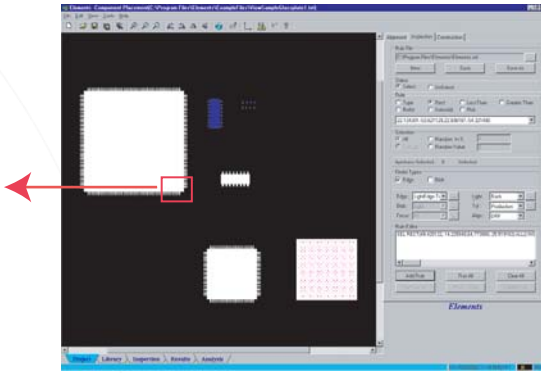
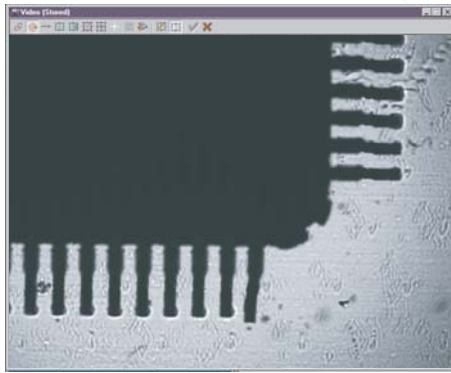


**S**ummit is a stand-alone vision-based measurement system for fast, precision measurement of stencils, screens, PCBs, solder paste, component placement machine accuracy, and electronic component packages. Elements™ Component Placement Measurement Software for Summit eliminates programming by providing CAD-driven measurement of component placement machine accuracy. The software provides both a tabular and graphical summary of results.



**CAD-driven  
measurement  
of component  
placement  
eliminates  
programming!**

# Component Placement Measurement System

## Capabilities:

- **NIST-traceable** measurement of component placement accuracy.
- **Point-and-click measurement** - import the placement file, select tolerances, and begin measuring placement accuracy in less than 5 minutes.
- Use with slugs on glass (IPC-9850), components on glass, or components on opaque boards.
- True position measurement accuracy is  $2.5 + L/200$  microns, where L = measuring length in mm.
- Measure placement of components as small as 0201.
- Measure placement accuracy on panels as large as 762 mm x 812 mm (30" x 32").
- Measure up to 7,500 placed components in less than 30 minutes.
- Measure 100% of the placed components; or define a subset based on position, size, component type, or randomized sampling.
- Import placement text files that define component X,Y and  $\theta$ .
- Accommodate rotated (from CAD data) PCBs.

## Coming Soon...

- Measure components in paste.
- Measure post re-flow components.



## Summit™ Component Placement

**Measurement System** combines very high quality optics, lighting, image processing, and high-velocity/acceleration stage motion to address production tolerances in the micron range and a wide variety of glass artifact/PCB materials, shapes, and thicknesses.



## Elements Software Modules\*

Elements software modules are available to enable to enable a single VIEW Micro-Metrology system to provide CAD-driven measurement of a variety of electronic assembly manufacturing steps including:

### Stencils/Screens

- Hole location and size
- Blockage
- Missing holes
- Stencil thickness

### PCBs

- Drilled holes and vias
- Pad location and size
- Layer registration
- Profiles

### Solder Paste/Glue Dot

- Registration and size
- Height and volume

### Component Placement

- Slugs on glass (IPC-9850)
- Components on glass
- Components on board
- Missing components

### Components

- QFP
- BGA
- SOIC
- Flip chip
- MCM

Import your CAD files...  
No programming required!

\*Send us your parts along with their CAD files for a FREE capability analysis.

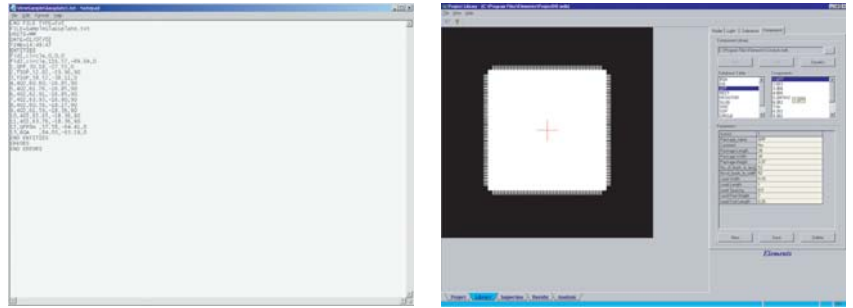
View has been providing precision measurement systems and solutions for process control on the shop floor for more than 25 years.

## Elements

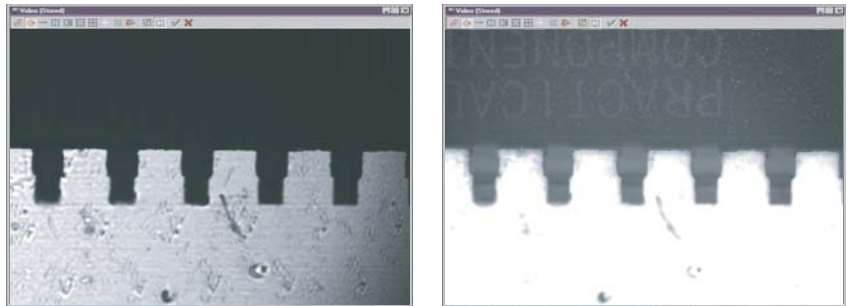
### Component Placement Measurement Software for Summit

This software module allows manufacturers or end users to measure component placement accuracy automatically by comparison with CAD-based data.

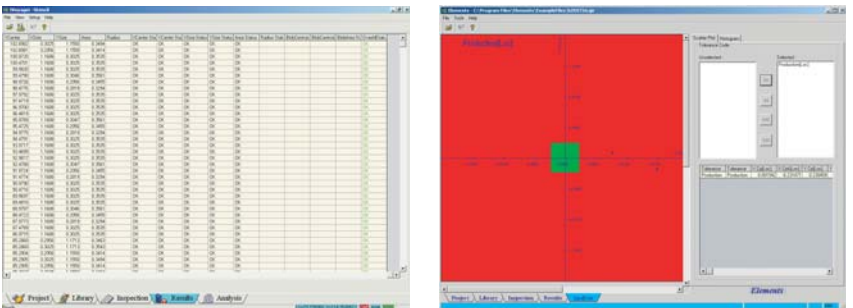
**STEP 1:** Import placement file and combine with the Elements Component Library.



**STEP 2:** Measure the placement of components on glass or opaque boards.



**STEP 3:** Review the automatically generated results summary & graphic analysis.



Improve your manufacturing process using this quantitative information!

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Improve yields.  
Reduce costs.  
Stay competitive.



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